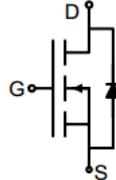


## N-Channel Enhancement Mode Power MOSFET

<p><b>Description</b></p> <p>This is a high voltage power MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in power supplies and adaptors.</p>	 Schematic Diagram		
<p><b>General Features</b></p> <ul style="list-style-type: none"> <li>● <math>V_{DS}</math> 400V</li> <li>● <math>I_D</math> (at <math>V_{GS} = 10V</math>) 9A</li> <li>● <math>R_{DS(ON)}</math> (at <math>V_{GS} = 10V</math>) &lt; 0.6Ω</li> <li>● 100% Avalanche Tested</li> <li>● RoHS Compliant</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>● Power switch</li> <li>● DC/DC converters</li> </ul>	 TO-220F		
<b>Device</b>	<b>Package</b>	<b>Marking</b>	<b>Packaging</b>
G9N40F-A	TO-220F	G9N40	50pcs/Tube

<b>Absolute Maximum Ratings</b> $T_C = 25^\circ\text{C}$ , unless otherwise noted			
Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	400	V
Continuous Drain Current	$I_D$	9	A
Pulsed Drain Current (note1)	$I_{DM}$	36	A
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Power Dissipation	$P_D$	134	W
Single Pulse Avalanche Energy (note3)	$E_{AS}$	120	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 To 150	°C

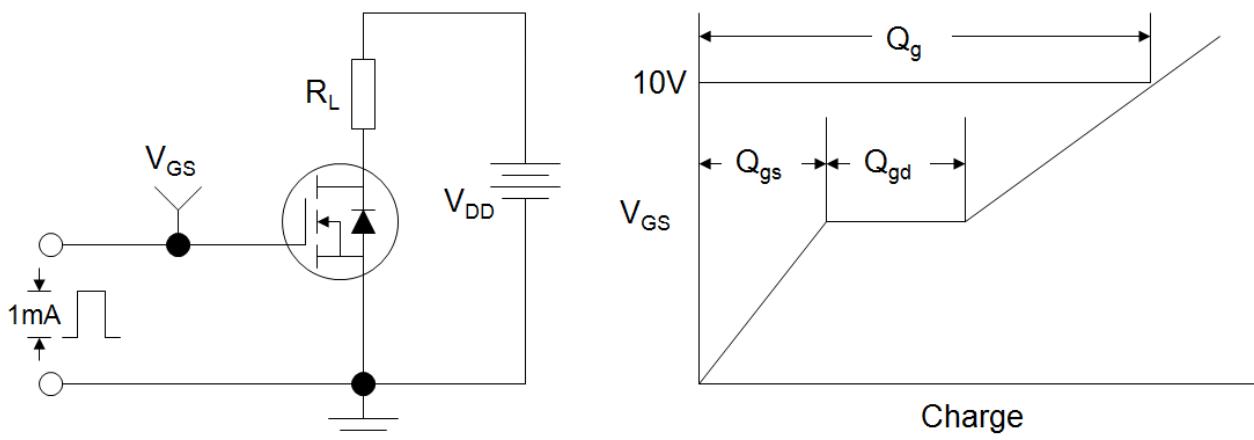
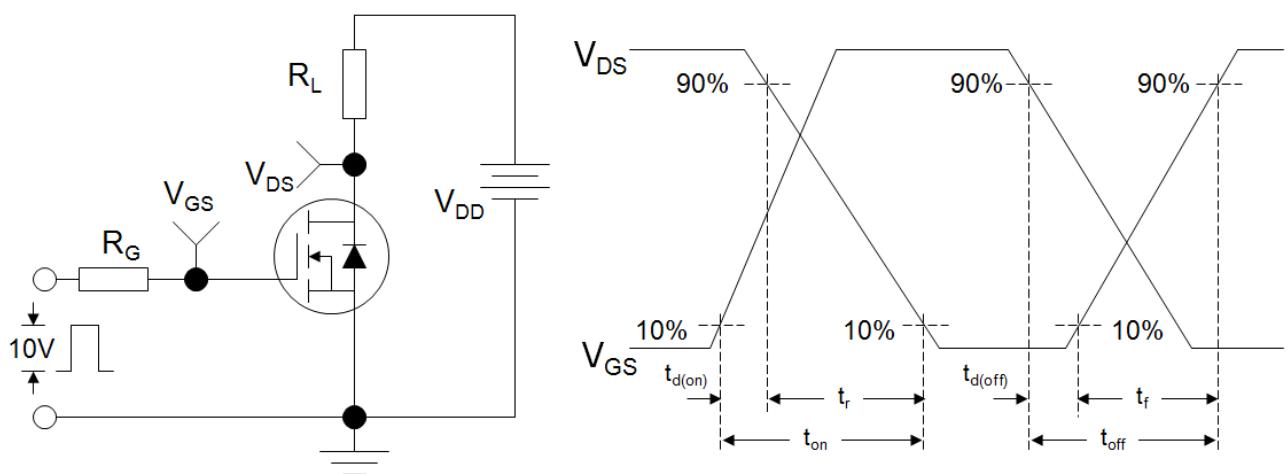
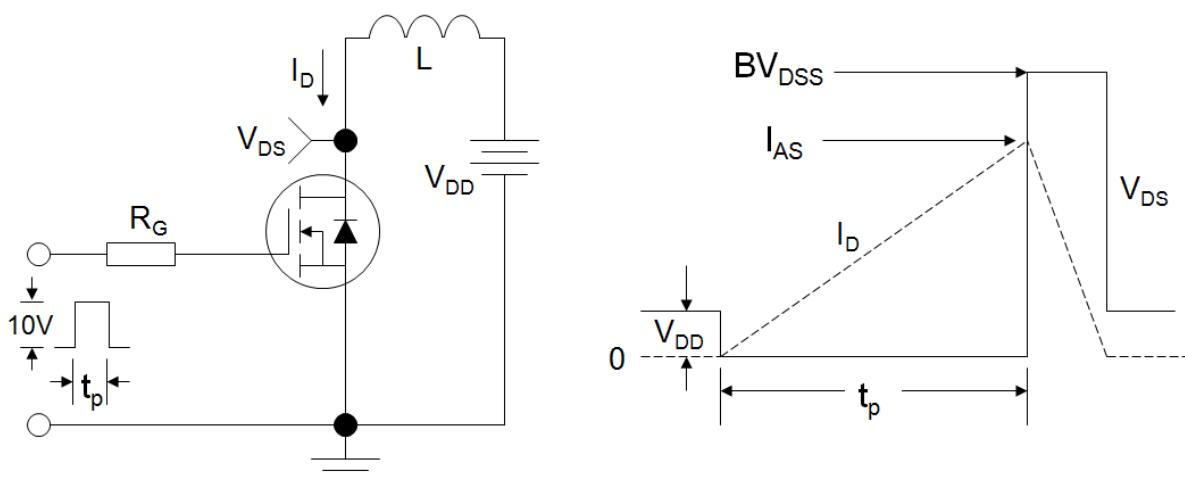
### Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{thJC}$	0.93	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	62.5	°C/W

<b>Specifications</b> $T_J = 25^\circ\text{C}$ , unless otherwise noted						
<b>Parameter</b>	<b>Symbol</b>	<b>Test Conditions</b>	<b>Value</b>			<b>Unit</b>
			<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	400	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 400\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	1	$\mu\text{A}$
Gate-Source Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 20\text{V}$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	0.5	1.5	2.5	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 5\text{A}$	--	0.47	0.6	$\Omega$
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1.0\text{MHz}$	--	893	--	pF
Output Capacitance	$C_{\text{oss}}$		--	116	--	
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	14	--	
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 320\text{V}, I_D = 5\text{A}, V_{\text{GS}} = 10\text{V}$	--	25	--	nC
Gate-Source Charge	$Q_{\text{gs}}$		--	2	--	
Gate-Drain Charge	$Q_{\text{gd}}$		--	11	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 200\text{V}, I_D = 5\text{A}, R_G = 25\Omega$	--	39	--	ns
Turn-on Rise Time	$t_r$		--	21	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	125	--	
Turn-off Fall Time	$t_f$		--	38	--	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$	$T_C = 25^\circ\text{C}$	--	--	9	A
Body Diode Voltage	$V_{\text{SD}}$	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 1\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.2	V

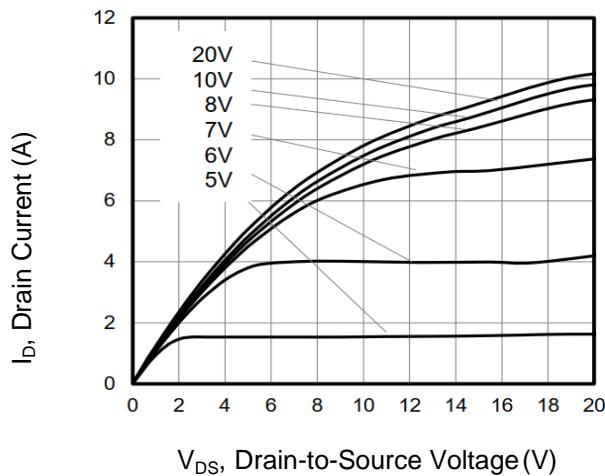
**Notes**

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Identical low side and high side switch with identical  $R_G$
3. EAS condition :  $T_J=25^\circ\text{C}, V_{\text{DD}}=50\text{V}, V_{\text{G}}=10\text{V}, L=0.5\text{mH}, R_g=25\Omega$

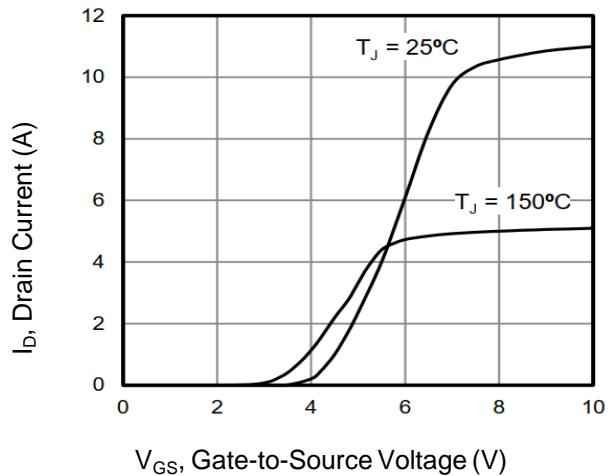
**Gate Charge Test Circuit****EAS Test Circuit****Switch TimeTest Circuit**

**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

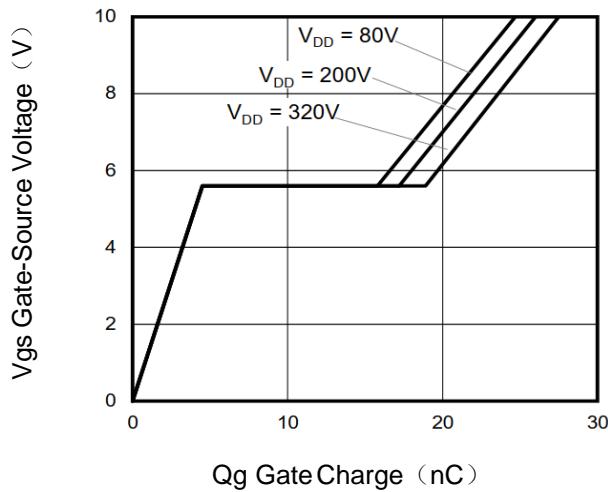
**Figure 1. Output Characteristics**



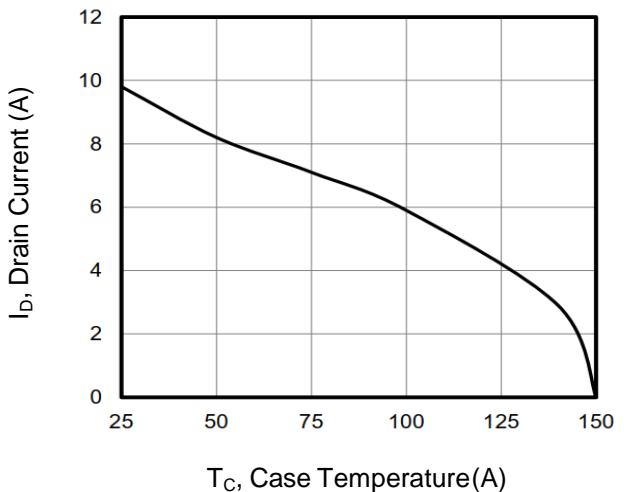
**Figure 2. Transfer Characteristics**



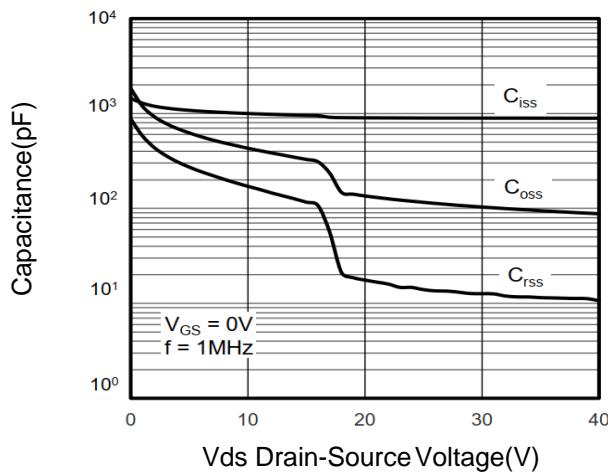
**Figure 3. Gate Charge**



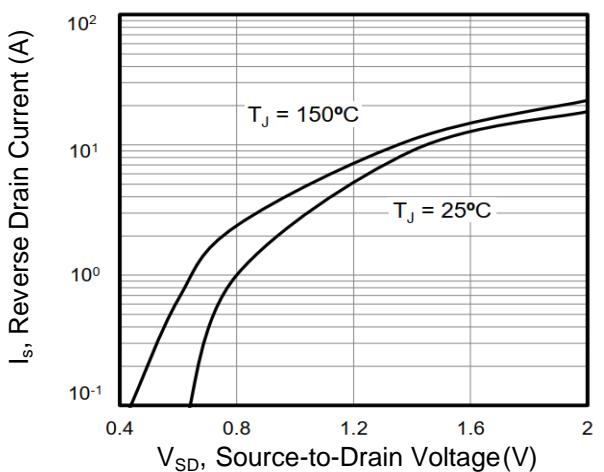
**Figure 3. Drain Current vs. Temperature**



**Figure 5. Capacitance vs Vds**

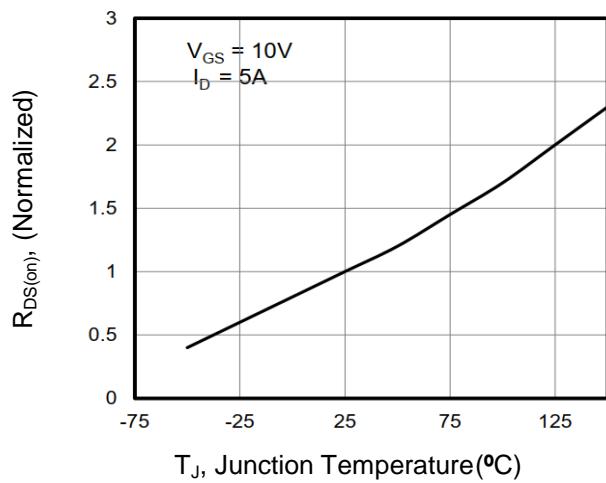


**Figure 6. Source-Drain Diode Forward**

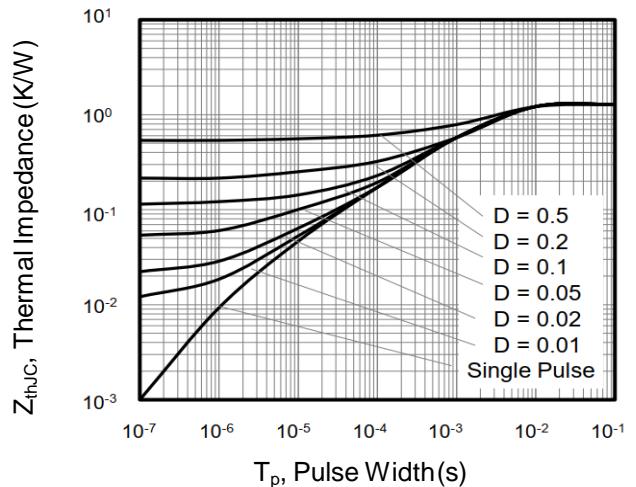


**Typical Characteristics**  $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

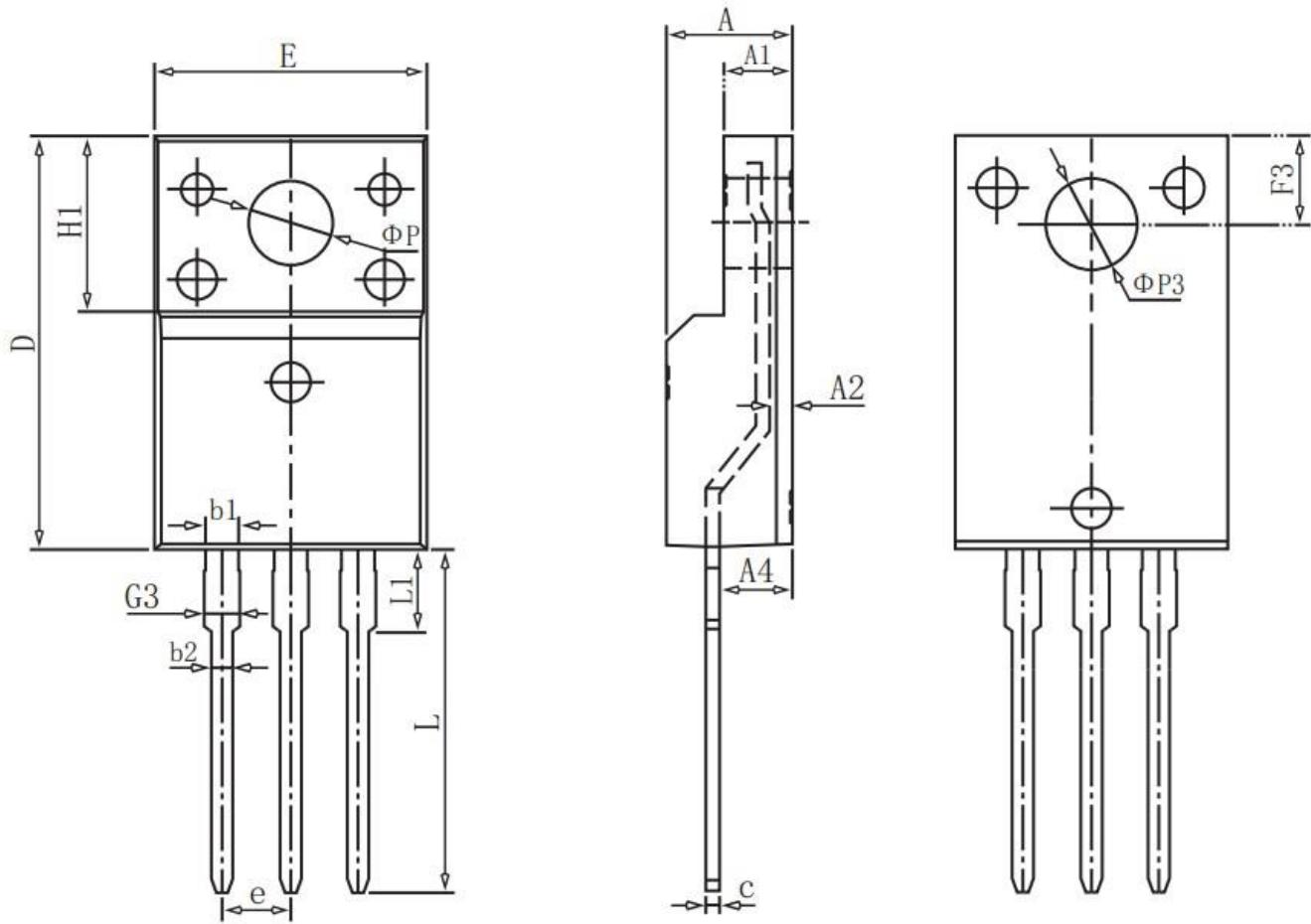
**Figure 7. Drain-Source On-Resistance**



**Figure 8. Transient Thermal Impedance**



## TO-220F Package Information



## COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
E	10.00	10.20	10.40
A	4.50	4.70	4.90
A1	2.34	2.54	2.74
A2	0.65	0.85	1.30
A4	2.55	2.75	2.95
c	0.40	0.50	0.65
D	15.57	15.87	16.17
H1		6.70REF	
e		2.54BSC	
Φ P		3.183REF	
L	12.68	12.98	13.28
L1	3.25	3.45	3.65
Φ P3		3.45REF	
F3	3.10	3.30	3.50
G3	1.10	1.30	1.50
b1	1.05	1.20	1.35
b2	0.70	0.80	0.92